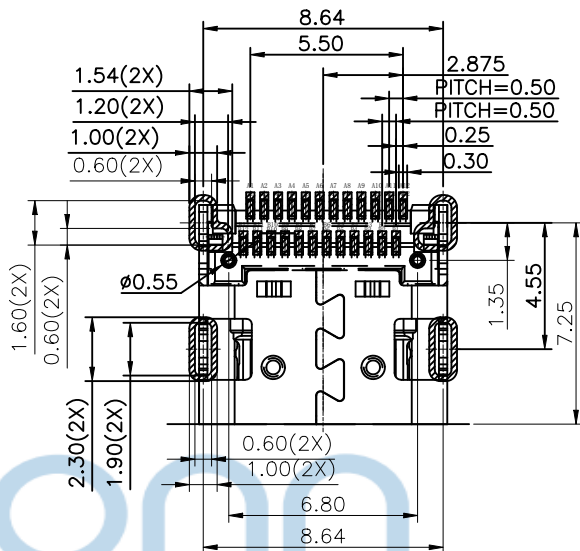
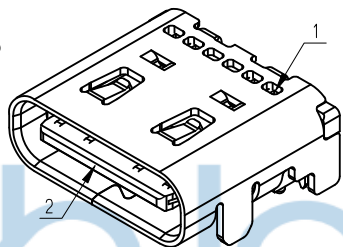
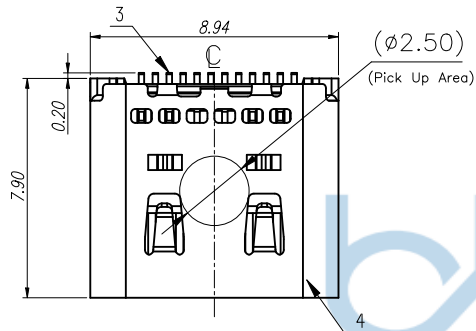
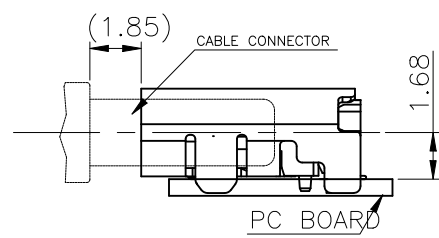
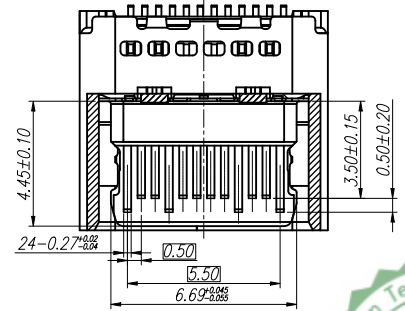
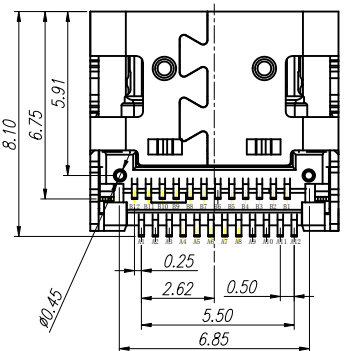
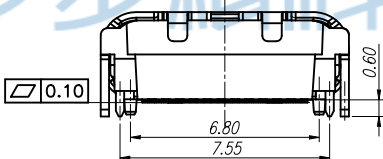
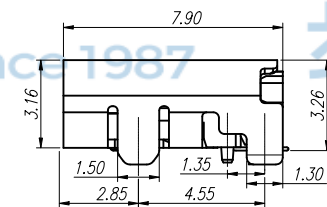
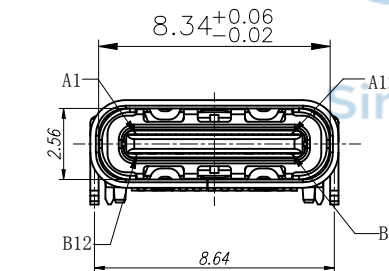


REV	ECN NO	CONTENT	DATE	ENGINEER
A0		INITIAL RELEASE	/	SGF



RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS 0.60MM;DEFAULT TOLERANCE:±0.05

- SPECIFICATION:
- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING: 5 A
 - TEMPERATURE RANGE: -40 °C ~ 85 °C
 - CONTACT RESISTANCE: 30 MILLIONHM MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 100 VAC r.m.s
 - INSULATION RESISTANCE: 100 MEGOHMS MIN.
 - MECHANICAL CHARACTERISTICS
 - INSERTION FORCE: 5~20N
 - EXTRACTION FORCE: Initial:8~20N,ATER TEST 6~20N
 - DURABILITY:10,000CYCLES
 - THE SHELL LENTH IS LESS THAN THE MINIMUM SPECIFIED BY THE USB TYPE C STANDARD.AS SUCH IS CANNOT INDENOENDENTLY BE GUARANTEED TO MEET ALL TYPE C MECHANICAL REQUIREMENTS.



RECESSED MOUNTING CONFIGURATION

PIN ASSIGNMENT			
Pin No.	Signal Name	Pin No.	Signal Name
A1	GND	B12	GND
A2	TX1+	B11	RX1+
A3	TX1-	B10	RX1-
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	D+	B7	D-
A7	D-	B6	D+
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	RX2-	B3	TX2-
A11	RX2+	B2	TX2+
A12	GND	B1	GND

Item	Description	QTY.	Material	Finish
4	Shielding plate	1	SUS 301	Ni underplating overall, Gold Flash plating on the solder tail.
3	Contact	24	C18400	Ni underplating overall, Au plating on the contact area, Gold Flash plating on the solder tail.
2	IM	1	LCP	UL94V-0, Black/White
1	Shell	1	SUS 304	Ni plating overall



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PDWG NO:0851-1

APPD: JM_Zheng
CHKD: Tang
DR: LYX

NAME: TYPE-C 24P 母座 L=7.90 板上四脚插 304 外壳带弹 端子双排SMT 无EMI片

PJ NO:126-221-160033-M3G
SIZE:A4
DRW NO:

FINISH:SEE NOTES
SCALE:N/A

MAT'L:SEE NOTES
REV:A0
UNIT:mm
PAGE:1/2

深圳市步步精科技有限公司

